



Material Content Data Sheet



Sales Product Name	BFP 750 H6327			Issued		29. August 2013		
MA#	MA000898760							
Package	PG-SOT343-4-2			Weight*		6.93 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	noble metal	gold	7440-57-5	0.003	0.04		389	
	non noble metal	tin	7440-31-5	0.001	0.01		100	
	inorganic material	silicon	7440-21-3	0.023	0.34	0.39	3388	3877
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		100	
	non noble metal	titanium	7440-32-6	0.003	0.05		498	
	non noble metal	chromium	7440-47-3	0.010	0.15		1493	
	non noble metal	copper	7440-50-8	3.433	49.56	49.77	495656	497747
wire	noble metal	gold	7440-57-5	0.008	0.11	0.11	1134	1134
encapsulation	organic material	carbon black	1333-86-4	0.030	0.44		4373	
	plastics	epoxy resin	-	0.651	9.40		94010	
	inorganic material	silicondioxide	60676-86-0	2.347	33.89	43.73	338872	437255
leadfinish	non noble metal	tin	7440-31-5	0.199	2.88	2.88	28764	28764
plating	noble metal	silver	7440-22-4	0.216	3.12	3.12	31223	31223
*deviation	< 10%	Sum in total:			100,00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com